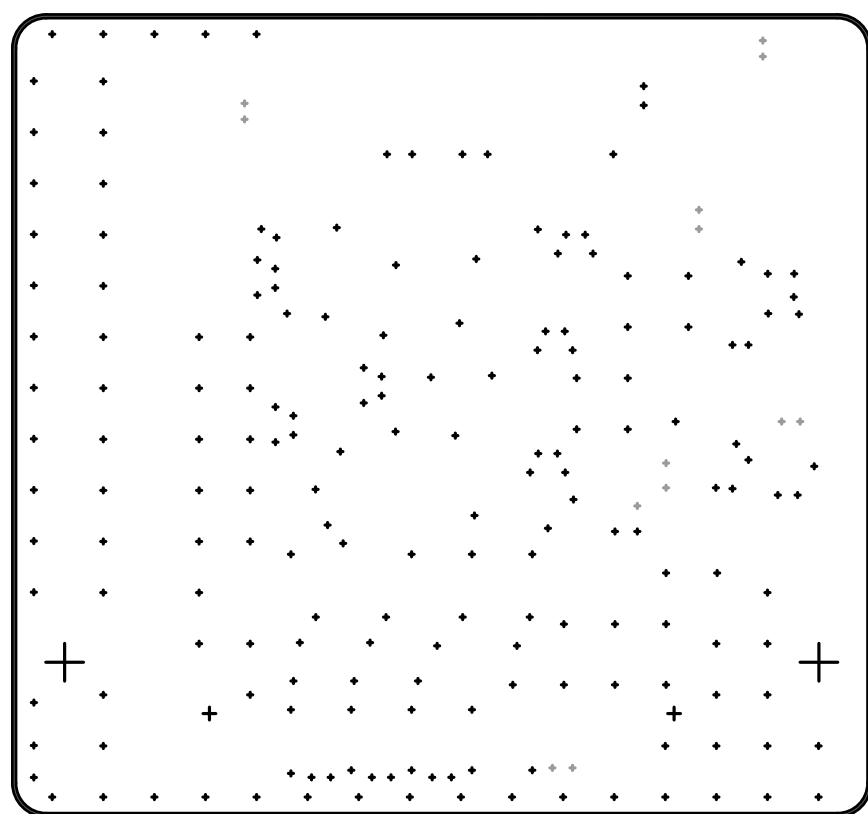


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.035mm		
	Dielectric 1	7628*1	0.210mm	4.05	
2	L02_GND	CF-004	0.015mm		
	Dielectric 2	Core	0.400mm	4.05	
3	L03_GND	CF-004	0.015mm		
	Dielectric 3	7628*1	0.210mm	4.05	
4	Bottom Layer	CF-004	0.035mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 0.970mm

LAYER	IMPEDANCE		WIDTH	SPACE
	SINGLE END	DIFF		
L1 & L4	-----	100 OHM	7.55 MILS	7.0 MILS

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
B	2	40.16mil (1.020mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
C	2	118.11mil (3.000mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
A	201	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	205 Total						



BOARD OUTLINE